

54ACT16543, 74ACT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCAS126B – MARCH 1990 – REVISED APRIL 1996

- Members of the Texas Instruments *Widebus*™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State True Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- *EPIC*™ (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'ACT16543 are 16-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ACT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch enable ($\overline{LEAB}$ or $\overline{LEBA}$) and output-enable ($\overline{OEAB}$ or $\overline{OEBA}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{CEAB}$) and $\overline{OEAB}$ inputs must be low to enter data from A or to output data to B. Having $\overline{CEAB}$ low and $\overline{LEAB}$ low makes the A-to-B latches transparent; a subsequent low-to-high transition at $\overline{LEAB}$ puts the A latches in the storage mode. Data flow from B to A is similar, but requires using the $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$ inputs.

The 74ACT16543 is packaged in TI's shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16543 is characterized for operation from –40°C to 85°C.

54ACT16543 . . . WD PACKAGE 74ACT16543 . . . DGG OR DL PACKAGE (TOP VIEW)

$\overline{1OEAB}$	1	56	$\overline{1OEBA}$
$\overline{1LEAB}$	2	55	$\overline{1LEBA}$
$\overline{1CEAB}$	3	54	$\overline{1CEBA}$
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
V_{CC}	7	50	V_{CC}
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V_{CC}	22	35	V_{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
$\overline{2CEAB}$	26	31	$\overline{2CEBA}$
$\overline{2LEAB}$	27	30	$\overline{2LEBA}$
$\overline{2OEAB}$	28	29	$\overline{2OEBA}$



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FUNCTION TABLE
(each octal register)

INPUTS			LATCH STATUS A TO B [†]	OUTPUT BUFFERS B1–B8
CEAB	LEAB	OEAB		
H	X	X	Storing	Z
X	H	X	Storing	Z
X	X	H	Transparent	Current A data
L	L	L	Storing	Previous A data [‡]
L	H	L		

[†] A-to-B data flow is shown: B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

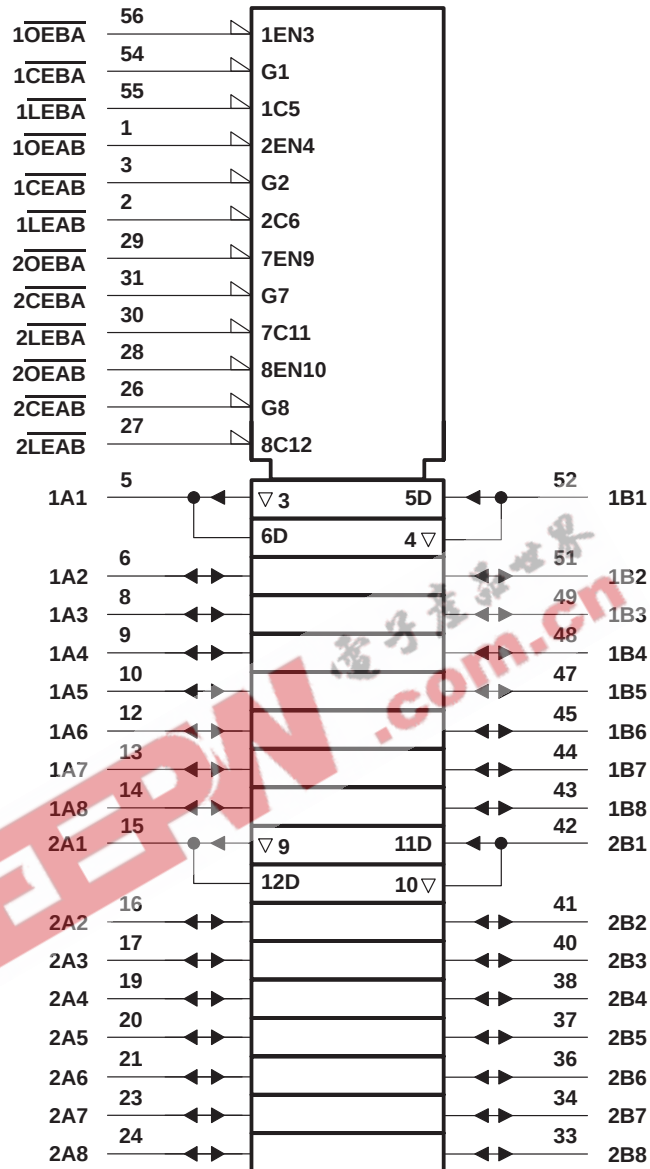
[‡] Data present before low-to-high transition of LEAB occurring while CEAB is low

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logic symbol[†]

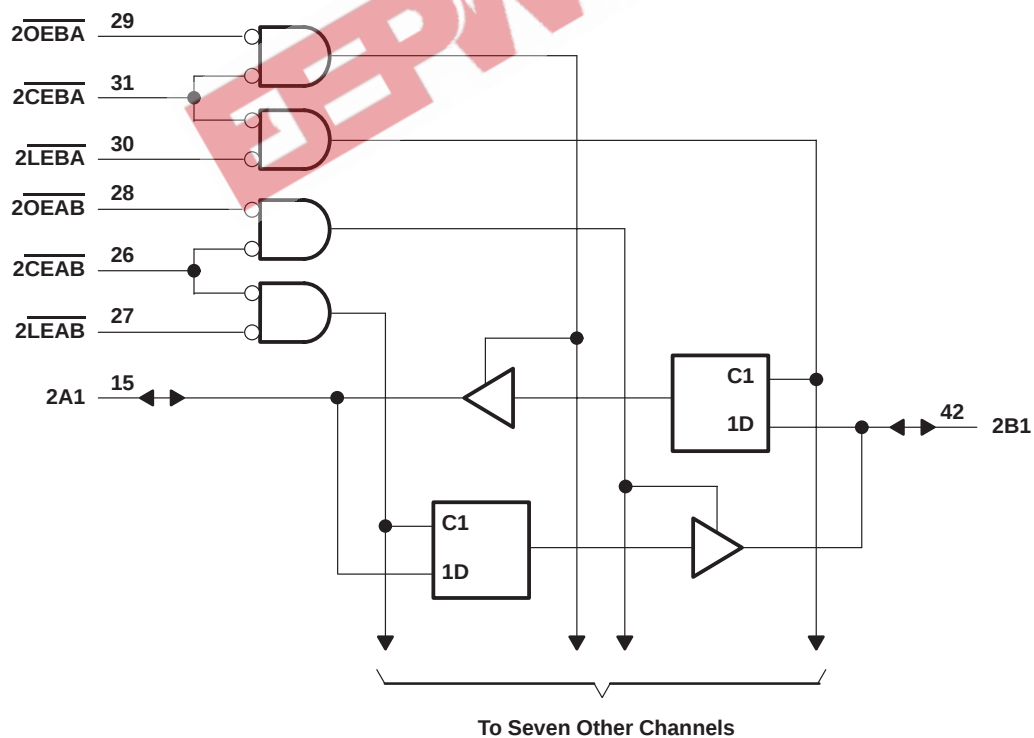
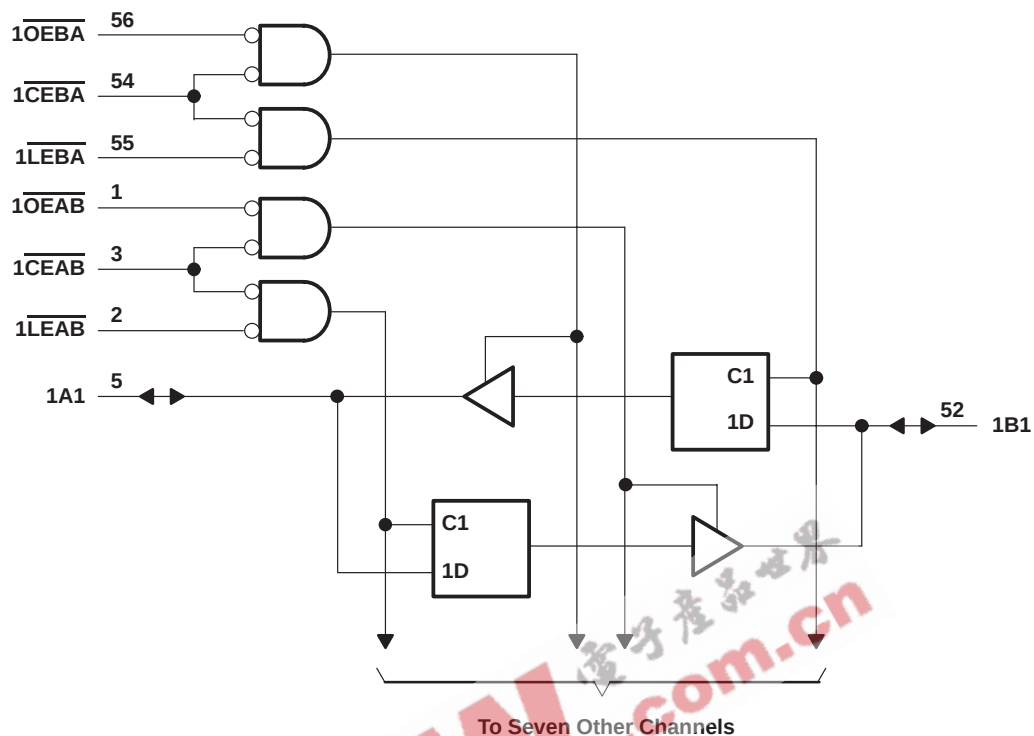


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC}+0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC}+0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

	54ACT16543			74ACT16543			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage (see Note 4)	4.5	5	5.5	4.5	5	5.5	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
V_I Input voltage	0		V_{CC}	0		V_{CC}	V
V_O Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH} High-level output current			–24			–24	mA
I_{OL} Low-level output current			24			24	mA
$\Delta t/\Delta v$ Input transition rise or fall rate	0		10	0		10	ns/V
T_A Operating free-air temperature	–55		125	–40		85	°C

- NOTES: 3. Unused pins (inputs and I/O) must be held high or low to prevent them from floating.
4. All V_{CC} and GND pins must be connected to the proper voltage power supply.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	T _A = 25°C			54ACT16543		74ACT16543		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}		I _{OH} = –50 µA	4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
		I _{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
			5.5 V	4.94			4.8		4.8		
		I _{OH} = –75 mA†	5.5 V				3.85		3.85		
V _{OL}		I _{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
		I _{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
			5.5 V			0.36		0.44		0.44	
		I _{OL} = 75 mA†	5.5 V				1.65		1.65		
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	µA
I _{OZ}	A or B ports‡	V _O = V _{CC} or GND	5.5 V			±0.5		±5		±5	µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V			8		80		80	µA
ΔI _{CC} §		One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			0.9		1		1	mA
C _i	Control inputs	V _I = V _{CC} or GND	5 V		4.5						pF
C _{io}	A or B ports	V _O = V _{CC} or GND	5 V		12						

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

§ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		T _A = 25°C		54ACT16543		74ACT16543		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ low	7.5		7.5		7.5		ns
t _{su}	Setup time, data before $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}\uparrow$	2.5		2.5		2.5		ns
t _h	Hold time, data after $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}\uparrow$	4		4		4		ns

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54ACT16543		74ACT16543		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	3.5	6.9	9.5	3.5	10.5	3.5	10.5	ns
t_{PHL}			3.1	7.3	10.7	3.1	11.6	3.1	11.6	
t_{PLH}	LEBA or LEAB	A or B	3.9	8.6	12.3	3.9	13.8	3.9	13.8	ns
t_{PHL}			3.9	8.7	12.2	3.9	13.5	3.9	13.5	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.6	7.1	10.3	2.6	11.4	2.6	11.4	ns
t_{PZL}			3.5	8.3	11.9	3.5	13.2	3.5	13.2	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	4.1	8.2	10.5	4.1	11.1	4.1	11.1	ns
t_{PLZ}			5	7.3	9.3	5	9.6	5	9.6	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	3.1	7.3	10.7	3.1	11.7	3.1	11.7	ns
t_{PZL}			3.9	8.5	12.2	3.9	13.5	3.9	13.5	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	4.6	8.5	11	4.6	11.6	4.6	11.6	ns
t_{PLZ}			5.2	7.4	9.7	5.2	10.5	5.2	10.5	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	45	pF
		Outputs disabled		12	

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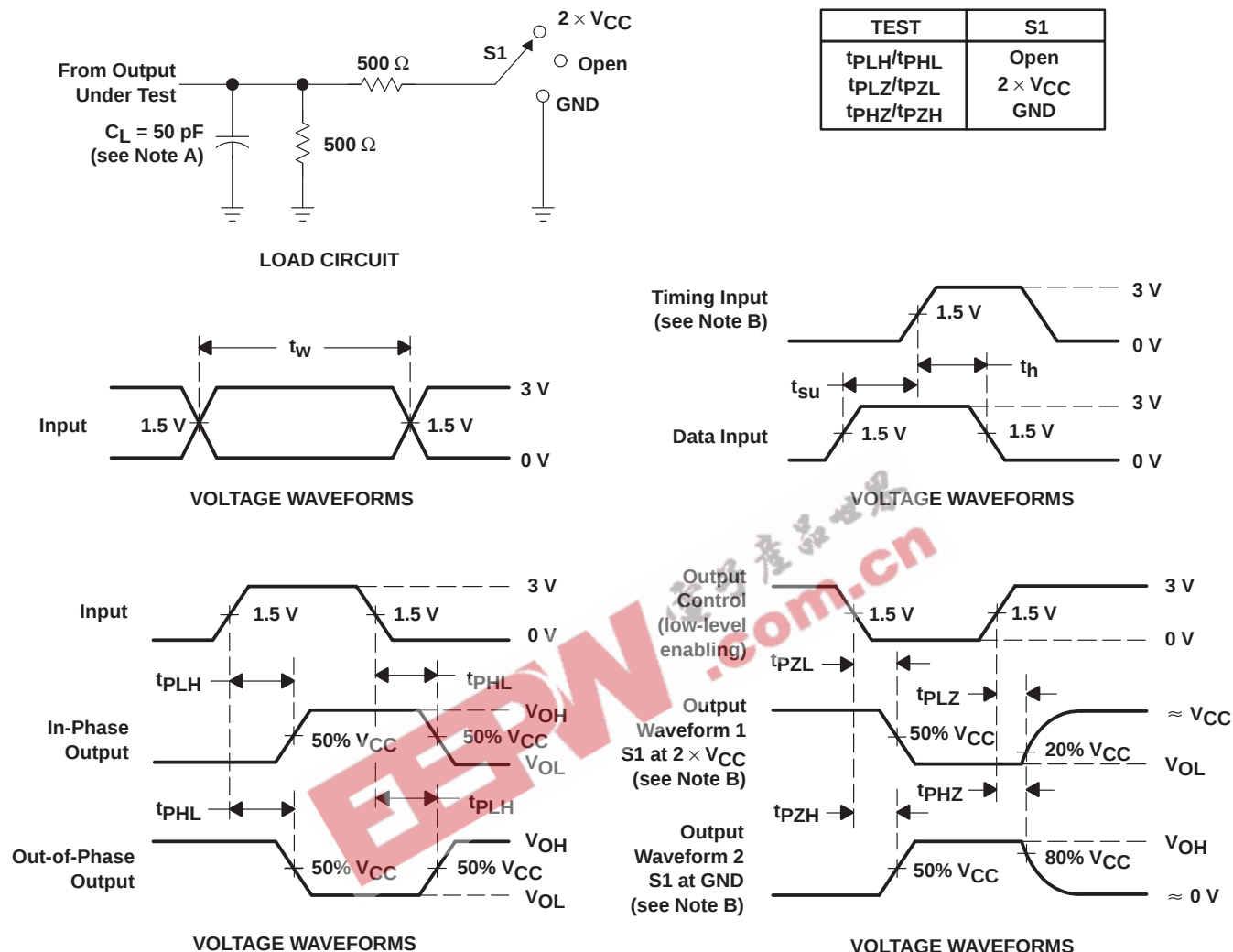


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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

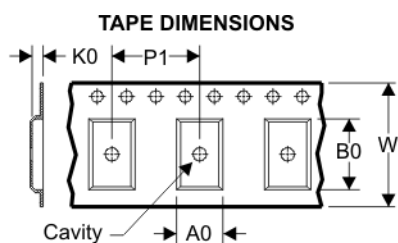
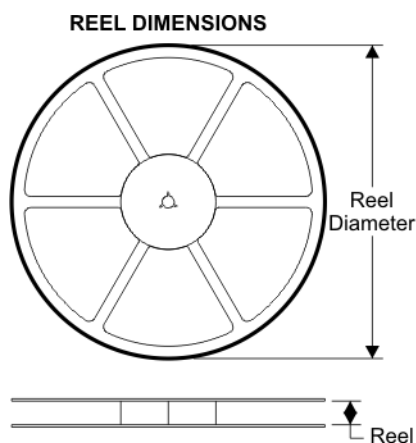
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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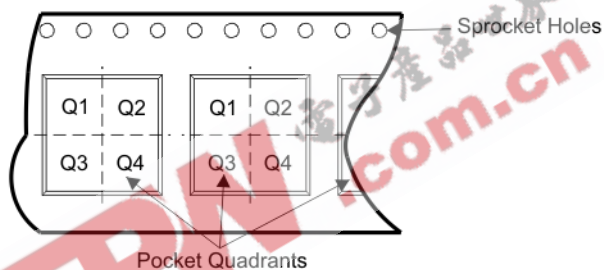
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TAPE AND REEL BOX INFORMATION



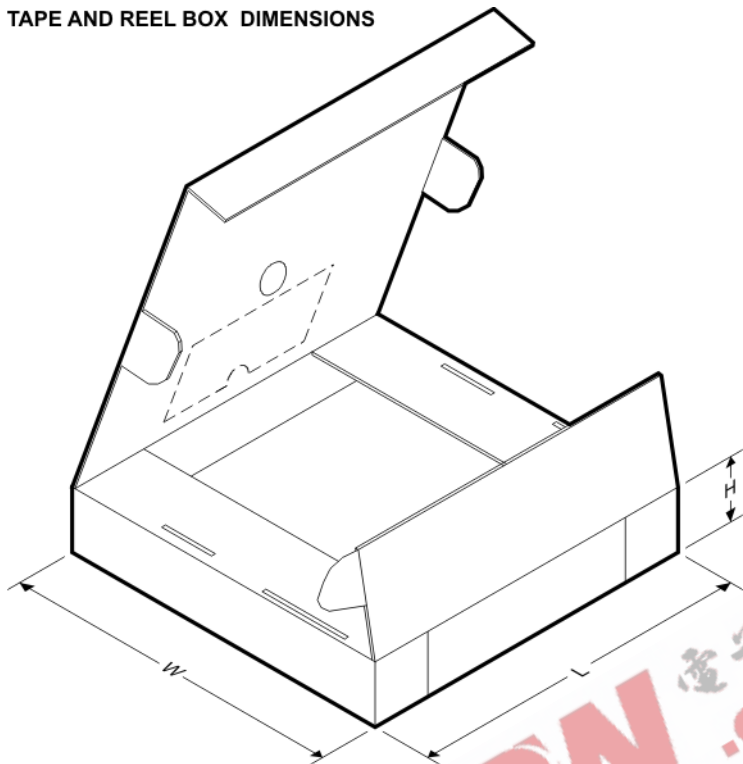
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16543DGGR	DGG	56	SITE 41	330	24	8.6	15.6	1.8	12	24	Q1
74ACT16543DLR	DL	56	SITE 41	330	32	11.35	18.67	3.1	16	32	Q1

TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
74ACT16543DGGR	DGG	56	SITE 41	346.0	346.0	0.0
74ACT16543DLR	DL	56	SITE 41	346.0	346.0	0.0

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